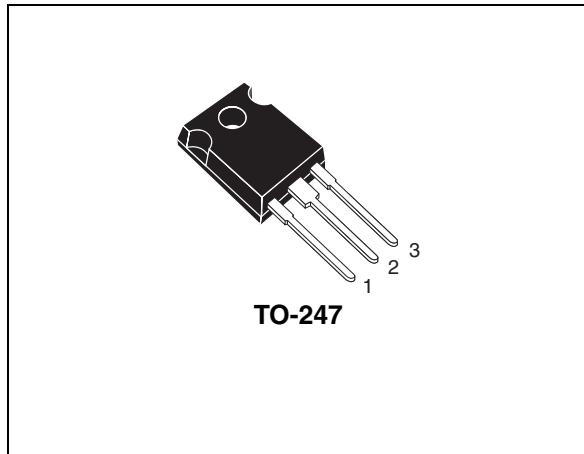


N-channel 650 V, 0.055 Ω , 49 A TO-247
FDmesh™ II Power MOSFET (with fast diode)

Features

Order code	V_{DSS} (@ T_{jmax})	$R_{DS(on)}$ max.	I_D
STW54NM65ND	710 V	< 0.065 Ω	49 A

- The worldwide best $R_{DS(on)}$ * area amongst the fast recovery diode devices
- 100% avalanche tested
- Low input capacitance and gate charge
- Low gate input resistance
- Extremely high dv/dt and avalanche capabilities



Application

Switching applications

Description

The device is an N-channel FDmesh™ II Power MOSFET that belongs to the second generation of MDmesh™ technology. This revolutionary Power MOSFET associates a new vertical structure to the company's strip layout and associates all advantages of reduced on-resistance and fast switching with an intrinsic fast-recovery body diode. It is therefore strongly recommended for bridge topologies, in particular ZVS phase-shift converters.

Figure 1. Internal schematic diagram

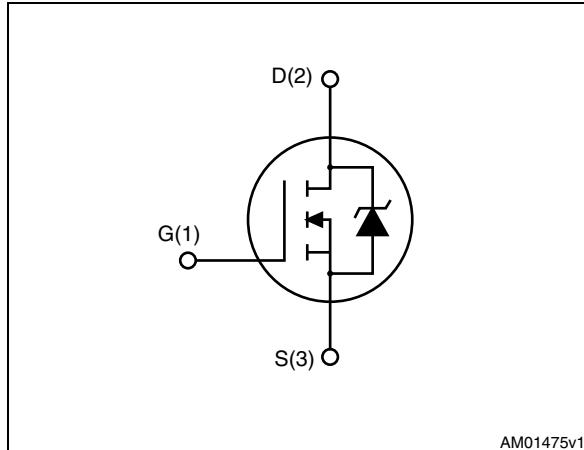


Table 1. Device summary

Order code	Marking	Package	Packaging
STW54NM65ND	54NM65ND	TO-247	Tube

1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage ($V_{GS} = 0$)	650	V
V_{GS}	Gate- source voltage	± 25	V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$	49	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	31	A
$I_{DM}^{(1)}$	Drain current (pulsed)	196	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	350	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	40	V/ns
T_{stg}	Storage temperature	- 55 to 150	$^\circ\text{C}$
T_j	Max. operating junction temperature	150	$^\circ\text{C}$

1. Pulse width limited by safe operating area
2. $I_{SD} \leq 49 \text{ A}$, $di/dt \leq 600 \text{ A}/\mu\text{s}$, $V_{DD} = 80\% V_{(BR)DSS}$

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	0.36	$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max	50	$^\circ\text{C}/\text{W}$
T_I	Maximum lead temperature for soldering purpose	300	$^\circ\text{C}$

Table 4. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AS}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max)	15	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AS}$, $V_{DD} = 50 \text{ V}$)	850	mJ

2 Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 5. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0$	650			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max rating}$ $V_{DS} = \text{Max rating, } @125^\circ\text{C}$			10 100	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20 \text{ V}$			100	nA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	3	4	5	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 24.5 \text{ A}$		0.055	0.065	Ω

Table 6. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 50 \text{ V}, f = 1 \text{ MHz},$ $V_{GS} = 0$	-	6200 218 10	-	pF pF pF
$C_{oss \text{ eq.}}^{(1)}$	Output equivalent capacitance	$V_{DS}=0 \text{ to } 200 \text{ V } V_{GS}=0$	-	850	-	pF
Q_g Q_{gs} Q_{gd}	Total gate charge Gate-source charge Gate-drain charge	$V_{DD} = 520 \text{ V}, I_D = 49 \text{ A},$ $V_{GS} = 10 \text{ V},$	-	188 32 100	-	nC nC nC
t_c t_r $t_{d(\text{off})}$ t_f	Crossing time Rise time Turn-off delay time Fall time	$V_{DD} = 520 \text{ V}, I_D = 49 \text{ A},$ $R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	33 59 152 98	-	ns ns ns ns
R_g	Gate input resistance	f=1 MHz gate DC bias=0 Test signal level = 20 mV open drain	-	1.9	-	Ω

1. $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DS} .

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min	Typ.	Max	Unit
I_{SD}	Source-drain current		-		49	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				196	A
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 49 \text{ A}, V_{GS} = 0$	-		1.3	V
t_{rr}	Reverse recovery time	$I_{SD} = 49 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		212		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 60 \text{ V}$	-	2		μC
I_{RRM}	Reverse recovery current			19		A
t_{rr}	Reverse recovery time	$I_{SD} = 49 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		296		ns
Q_{rr}	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	-	4		μC
I_{RRM}	Reverse recovery current			28		A

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

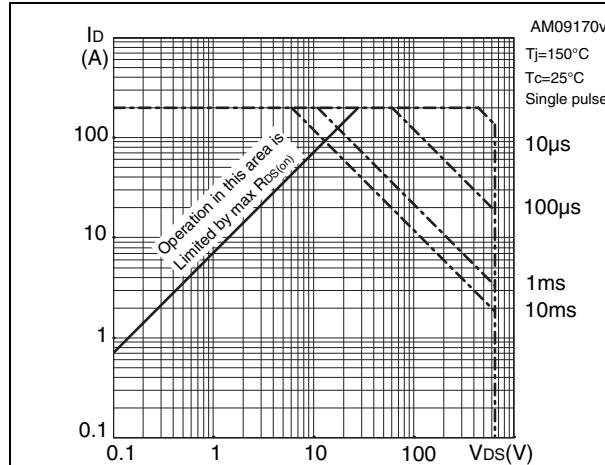


Figure 3. Thermal impedance

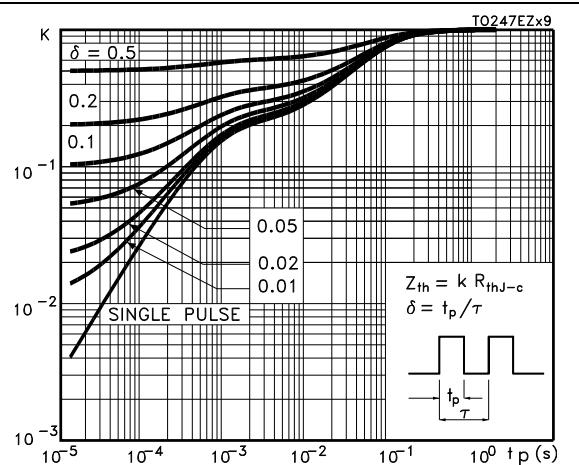


Figure 4. Output characteristics

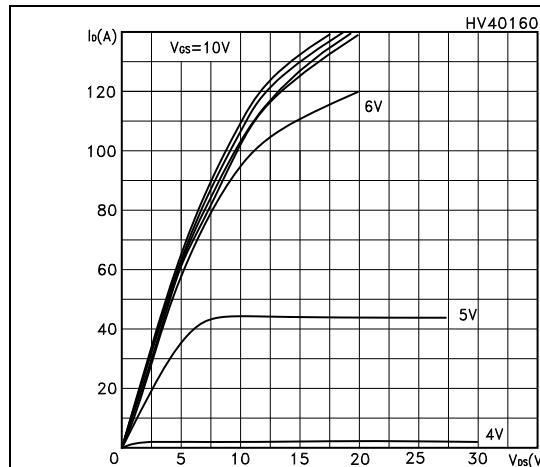


Figure 5. Transfer characteristics

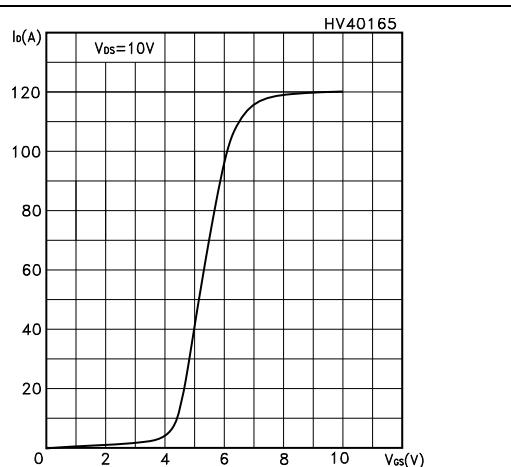


Figure 6. Normalized B_{VDSS} vs temperature

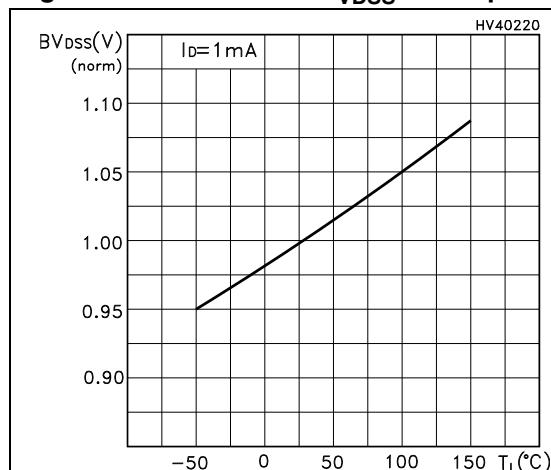


Figure 7. Static drain-source on resistance

